

Design For Testability

2011.06.03

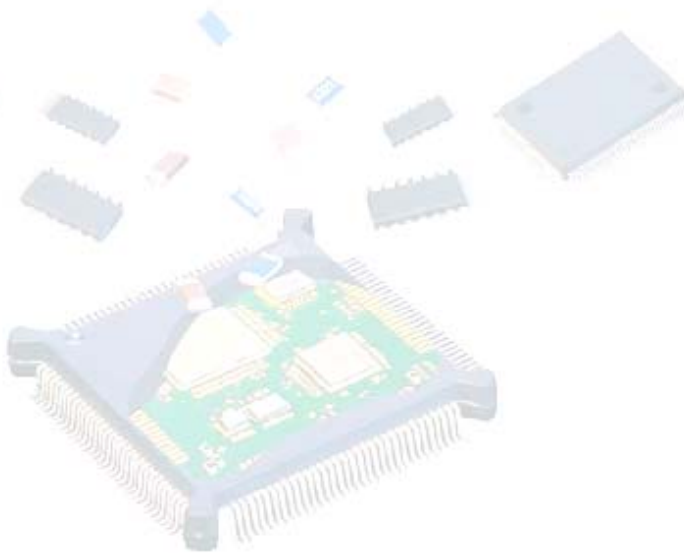
Sungho Kang



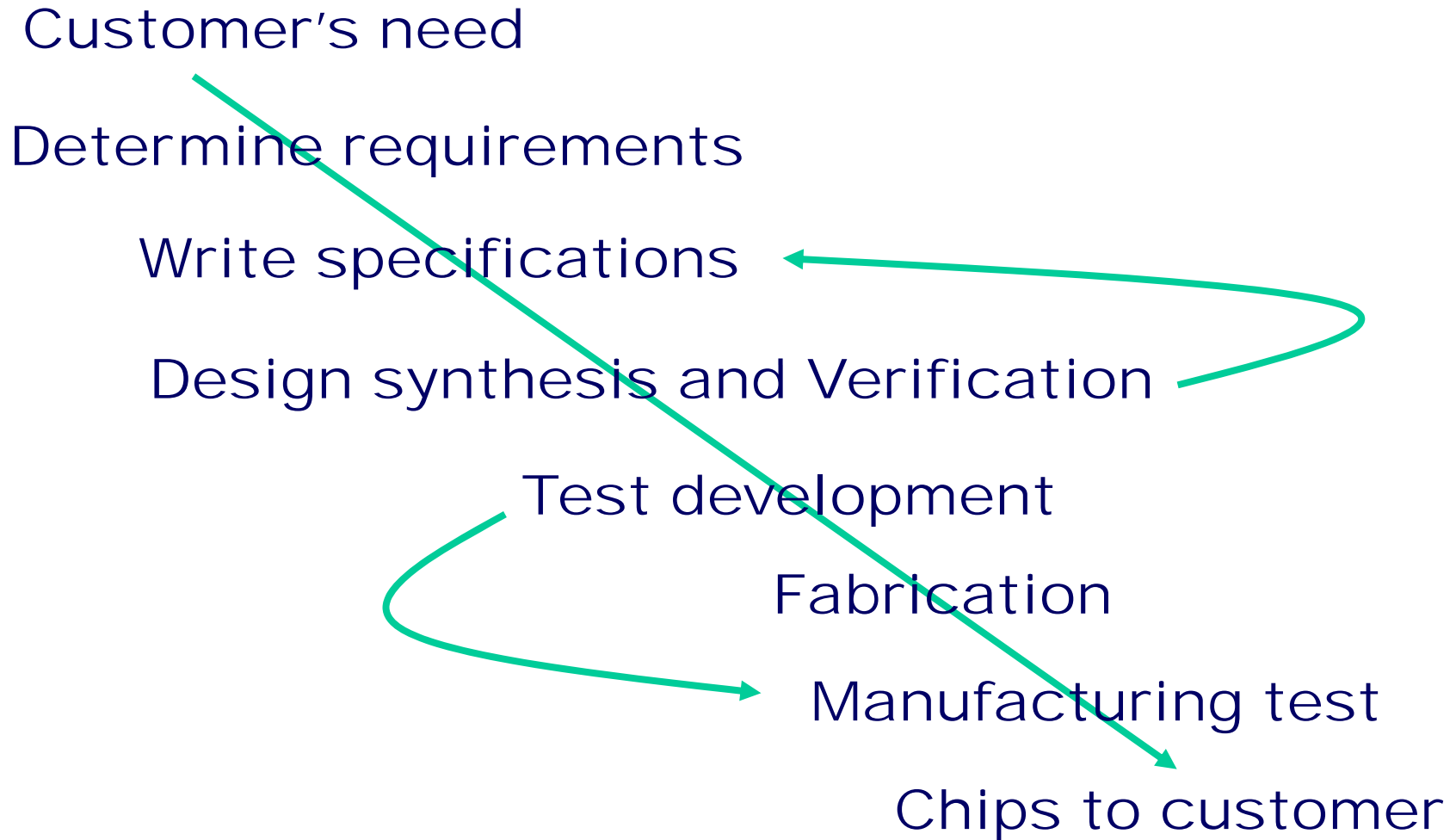
**COMPUTER SYSTEMS &
RELIABLE SOC LAB.**

Agenda

- Introduction
- Test Methodology
- Design for Testability
- IEEE P1500
- Case Study
- Conclusion



VLSI Implementation



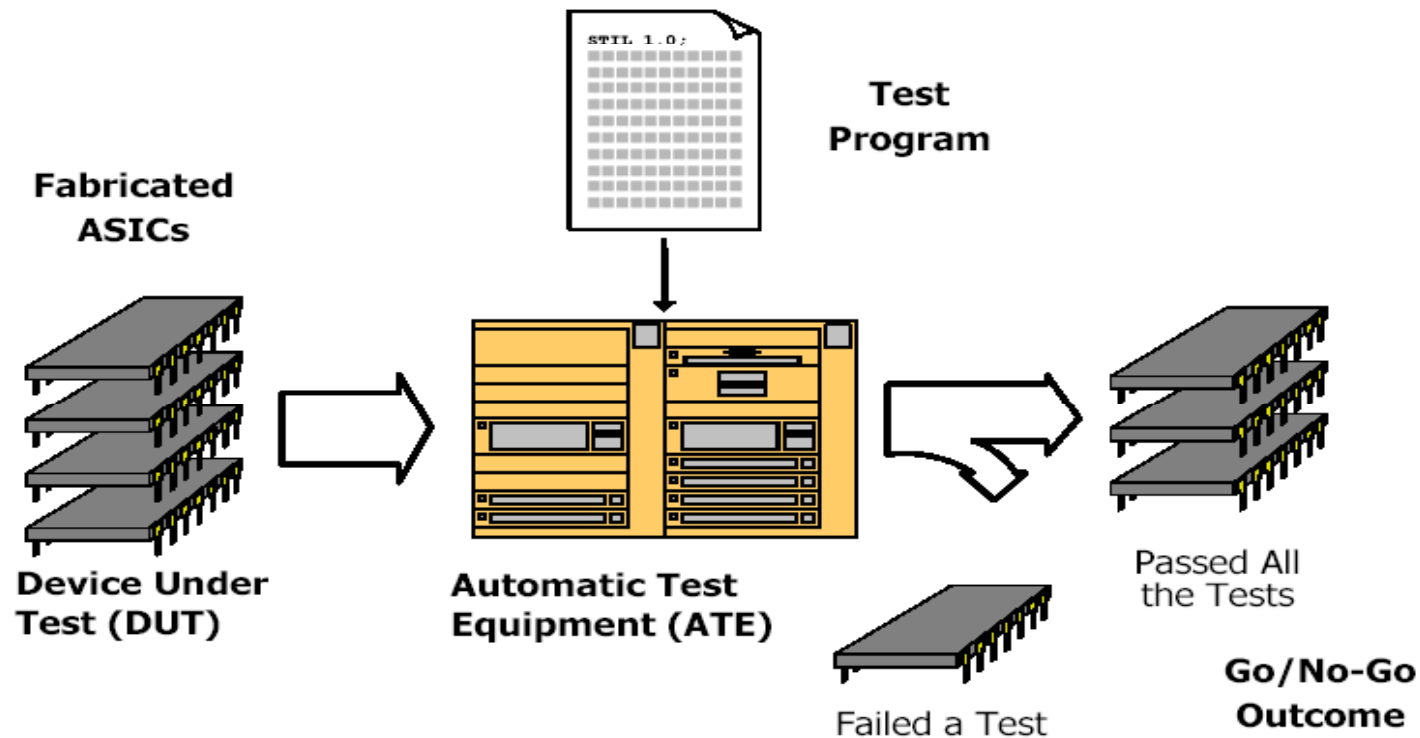
Design Constraints

- ◆ **Area**
- ◆ **Speed**
- ◆ **Power**
- ◆ **Testability**

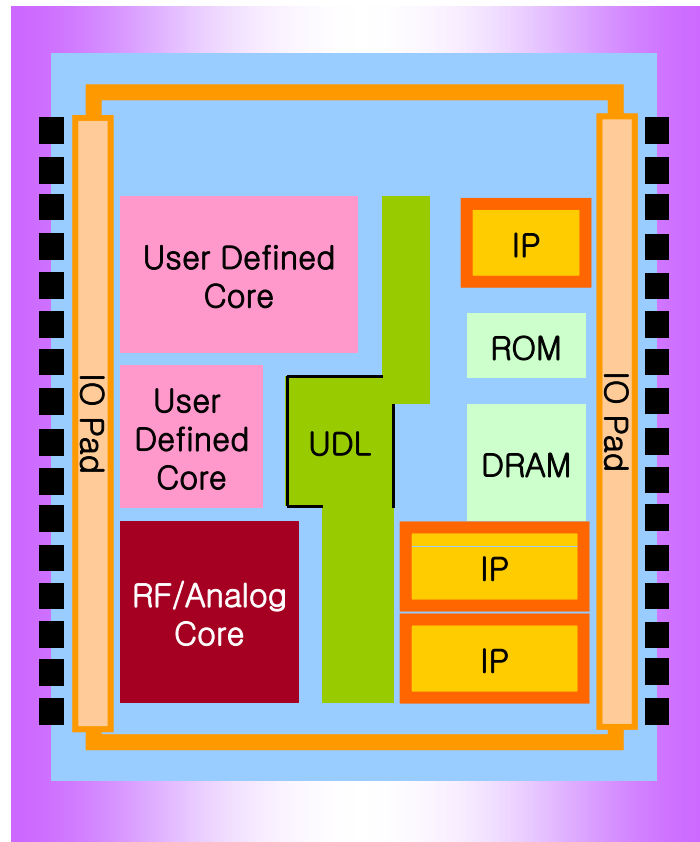


Testing Process

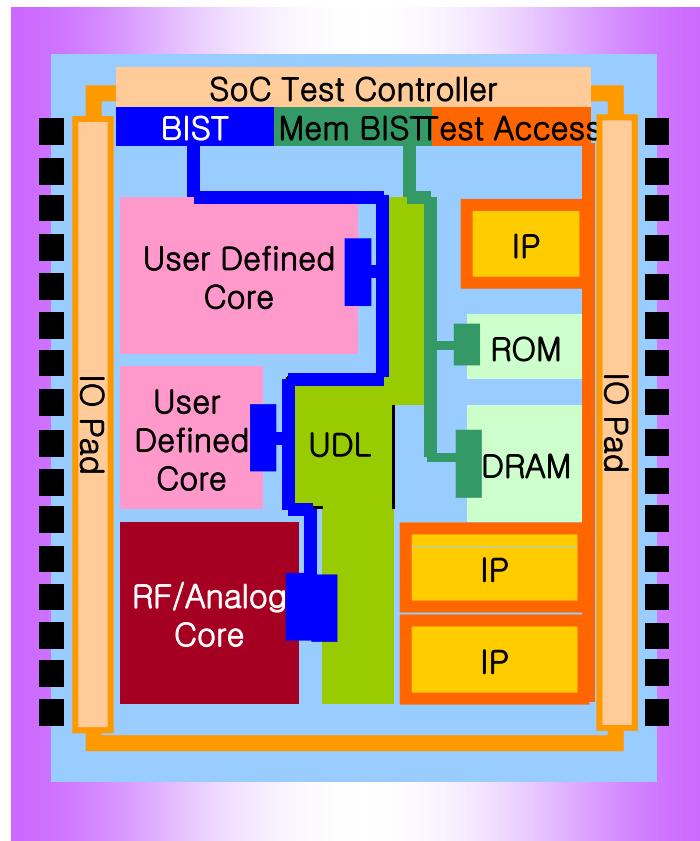
- ◆ Rule of thumb: spend 5-10% die area on DFT (10% of die is state and scan is 50% overhead per state!)



SOC Design

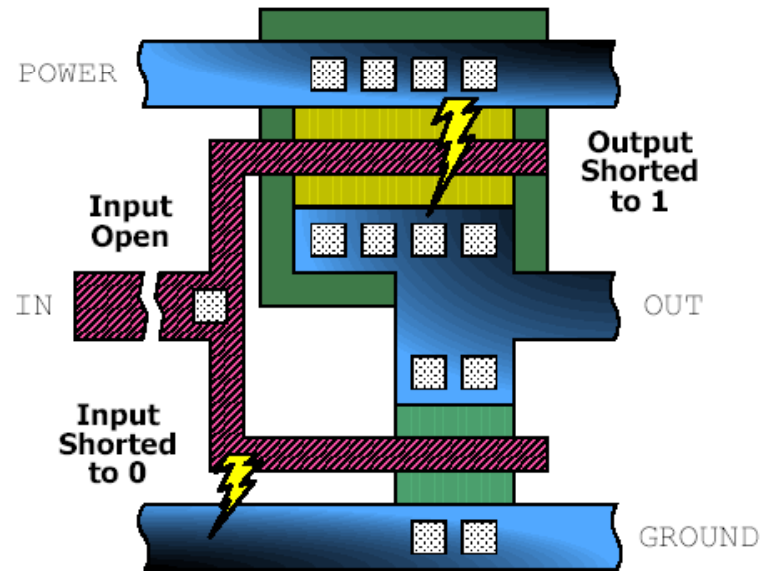


DFT for SOC



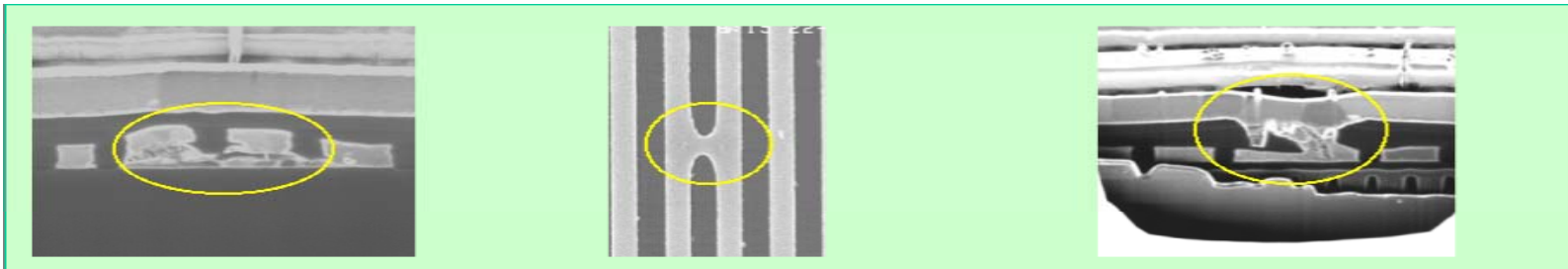
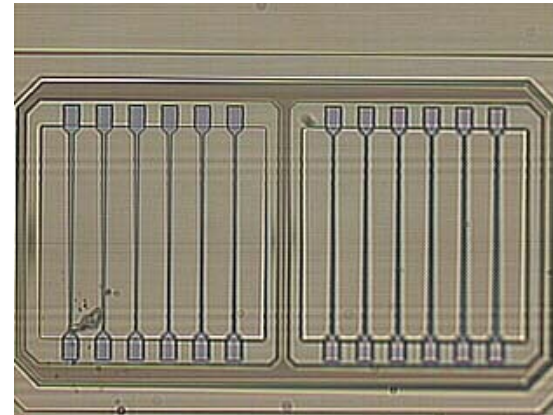
Manufacturing Defects

- ◆ In fabrication, defects get introduced from many sources:
 - Contamination
 - Metalization Defect
 - Implant Defect
 - Wafer Defect
 - Oxide Defect
 - Interconnect Defect

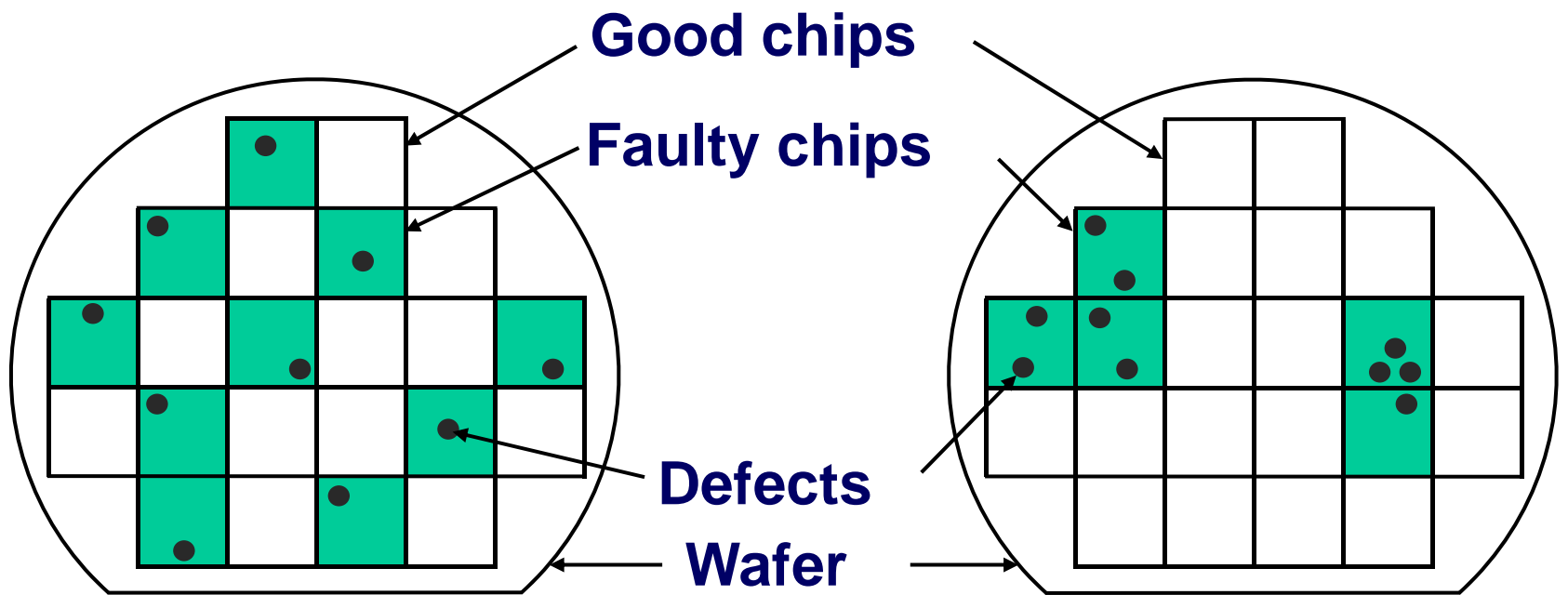


Defect & Fault

- ◆ Permanent
- ◆ Intermittent
- ◆ Temporary



Clustered VLSI Defects



Unclustered defects
Wafer yield = $12/22 = 0.55$

Clustered defects (VLSI)
Wafer yield = $17/22 = 0.77$



◆ Verification

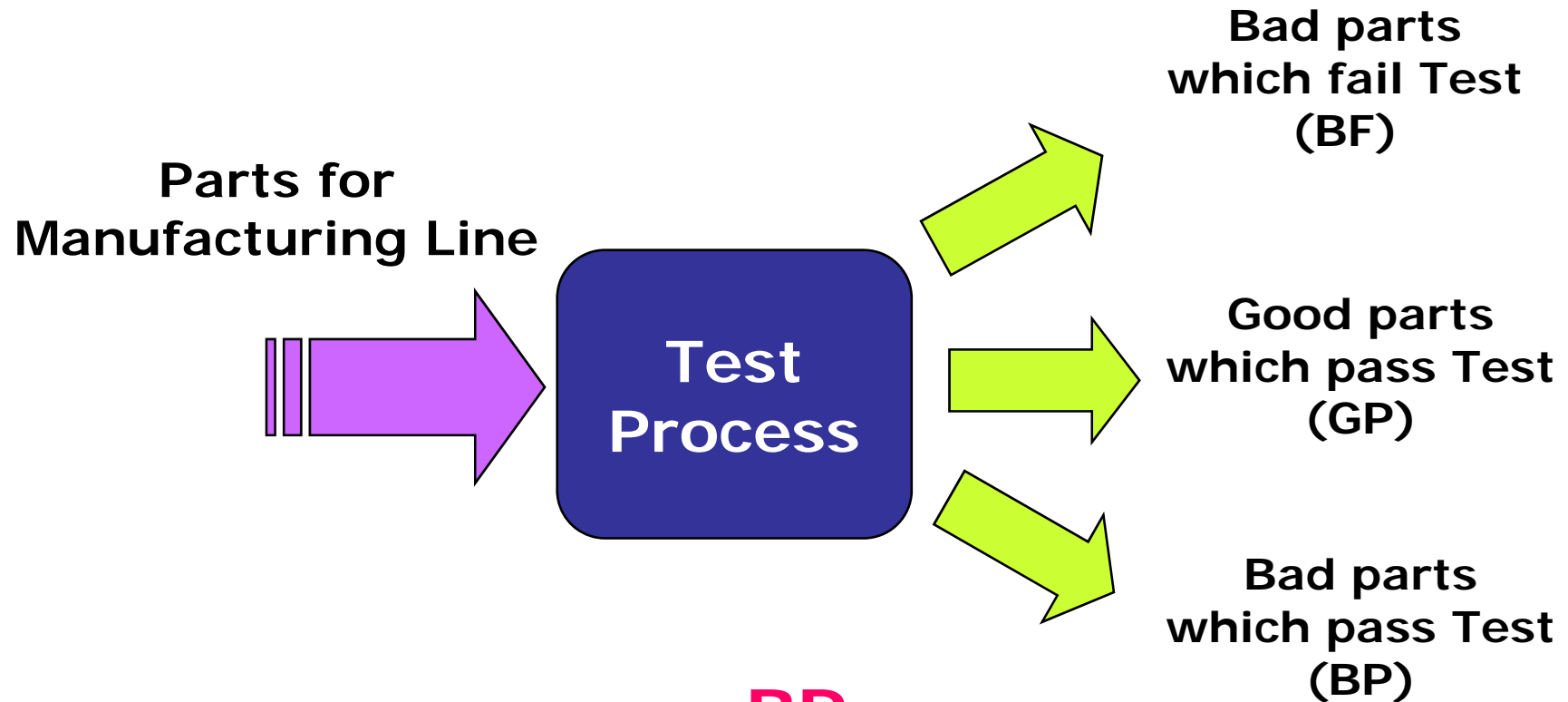
- Correctness of design
- Simulation, Emulation and Formal verification
- Performed once before manufacturing
- Responsible for quality of design

◆ Test

- Correctness of manufactured hardware
- Test generation and test application
- Performed every manufactured devices
- Responsible for quality of devices



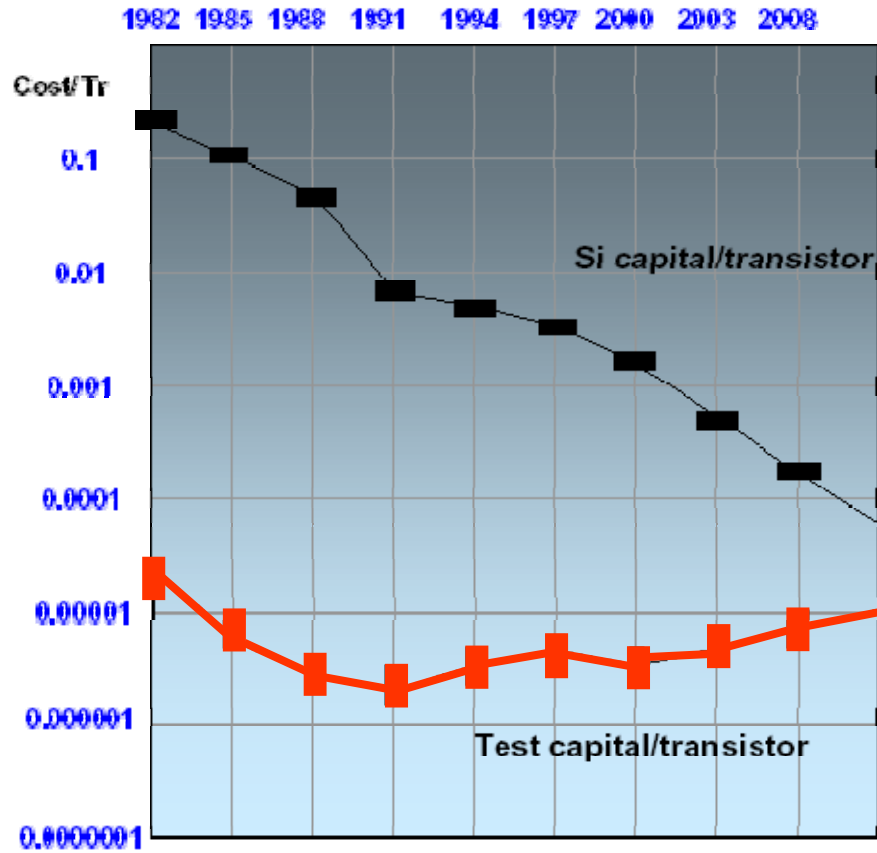
Test Process



$$\text{Defect Level} = \frac{\text{BP}}{\text{GP} + \text{BP}}$$

Test Cost vs Manufacturing Cost

Capital Investment for Manufacturing Test



1997 Microprocessor Cost of Test trend Model [2000 ITRS]



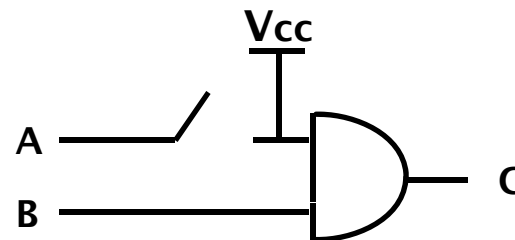
Single Stuck-at Fault (SSF)

- ◆ Only one line in the circuit is faulty at a time
- ◆ The fault is permanent (as opposed to transient)
- ◆ The effect of the fault is as if the faulty node is tied to either V_{cc} (s-a-1), or Gnd (s-a-0)
- ◆ The function of the gates in the circuit is unaffected by the fault

Fault: A s-a-1

A	B	C
0	0	0
0	1	0
1	0	0
1	1	1

Fault-Free Gate



A	B	C
0	0	0
0	1	1
1	0	0
1	1	1

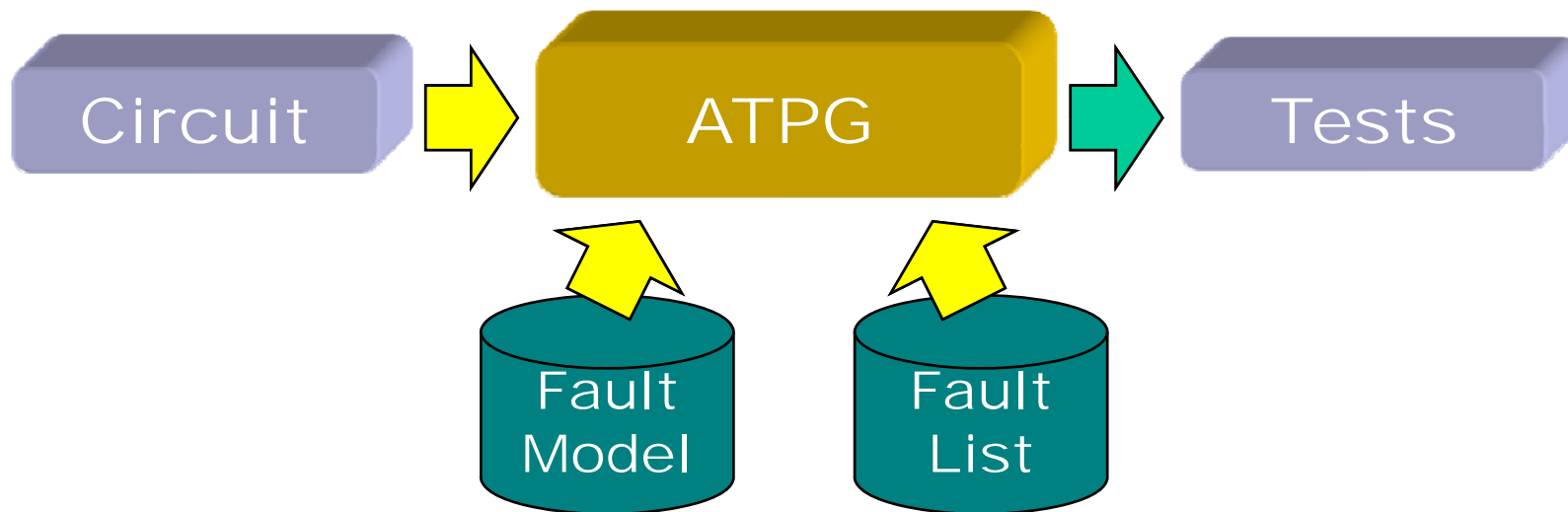
Faulty Gate



ATPG

◆ Automatic Test Pattern Generation (ATPG)

- Calculate the set of test patterns from a description of the logic network and a set of assumptions called fault models

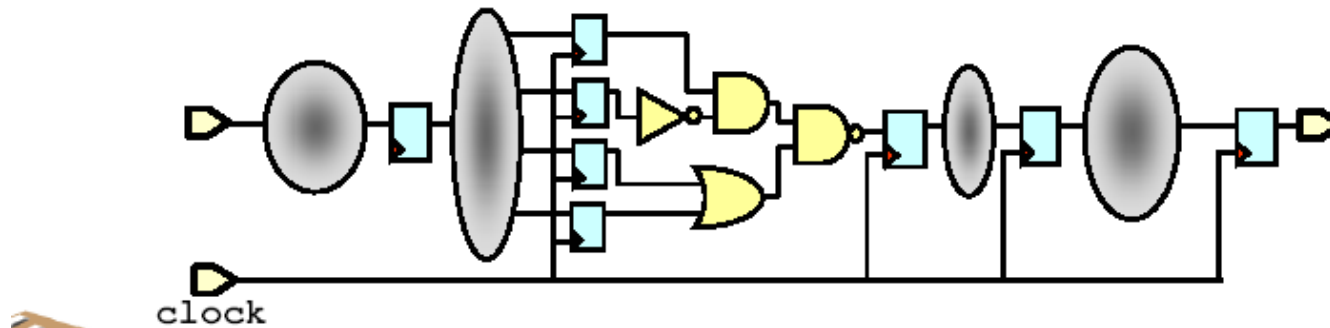


Sequential ATPG

To detect a stuck-at fault in synchronous **sequential** logic, we can still use the familiar D algorithm, but it'll take....

- One or more clock cycles to **activate** the fault.
- One or more clock cycles to **propagate** the fault effect.

In general, we'll need a **sequence** of patterns to detect a fault!



Design-for-Testability (DFT)

◆ Definition

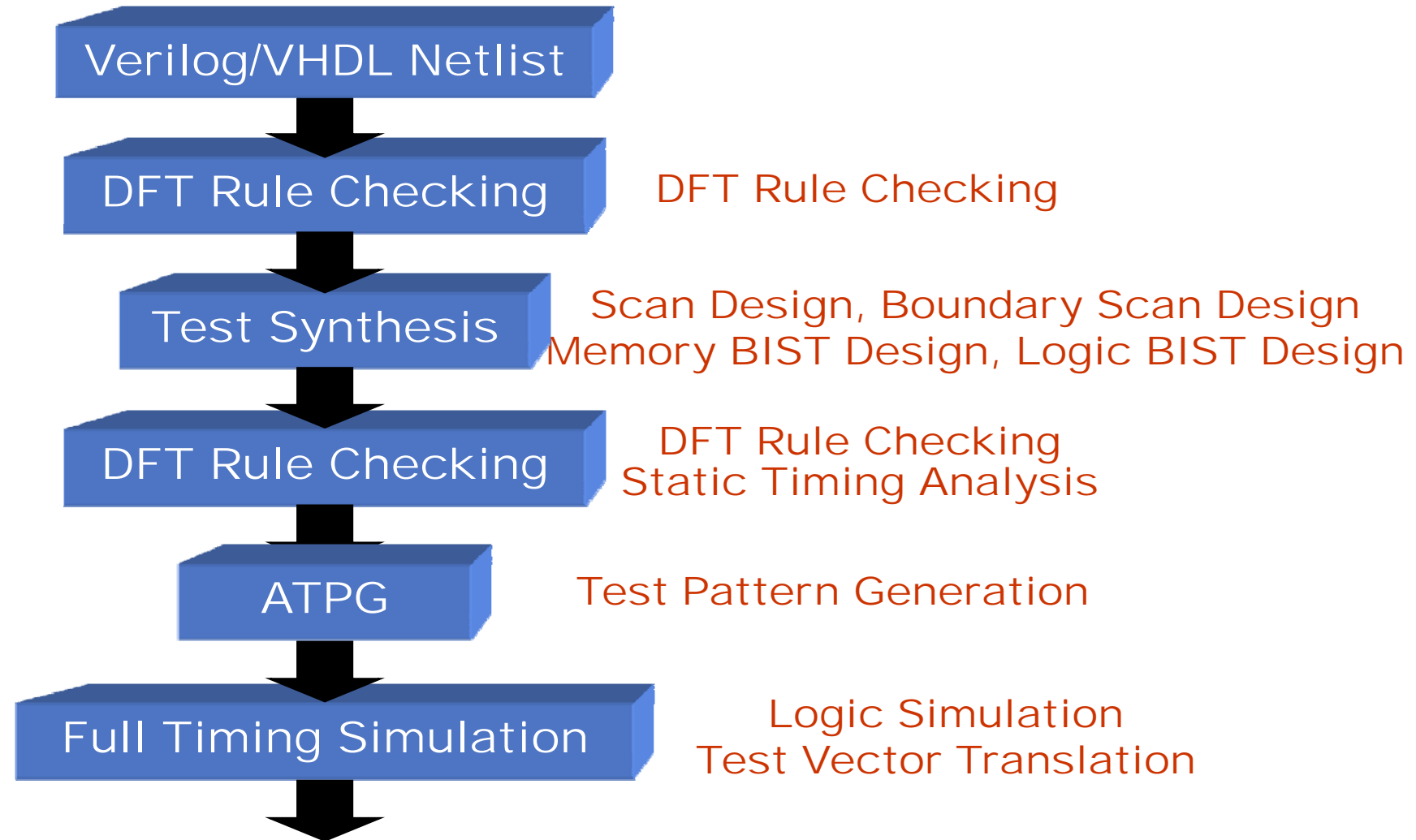
- Any design effort to reduce test costs
- The process of including special features to make a device easily testable

◆ Objective

- To reduce in overall design cycle times and test costs without sacrificing the quality of the product



DFT Flow



Ad-Hoc DFT Methods

- ◆ **Good design practices learnt through experience are used as guidelines:**

- ✓ Avoid asynchronous (unclocked) feedback.
- ✓ Make flip-flops initializable.
- ✓ Avoid redundant gates. Avoid large fanin gates.
- ✓ Provide test control for difficult-to-control signals.
- ✓ Avoid gated clocks.
- ✓ Consider ATE requirements (tristates, etc.)

- ◆ **Design reviews conducted by experts or design auditing tools.**

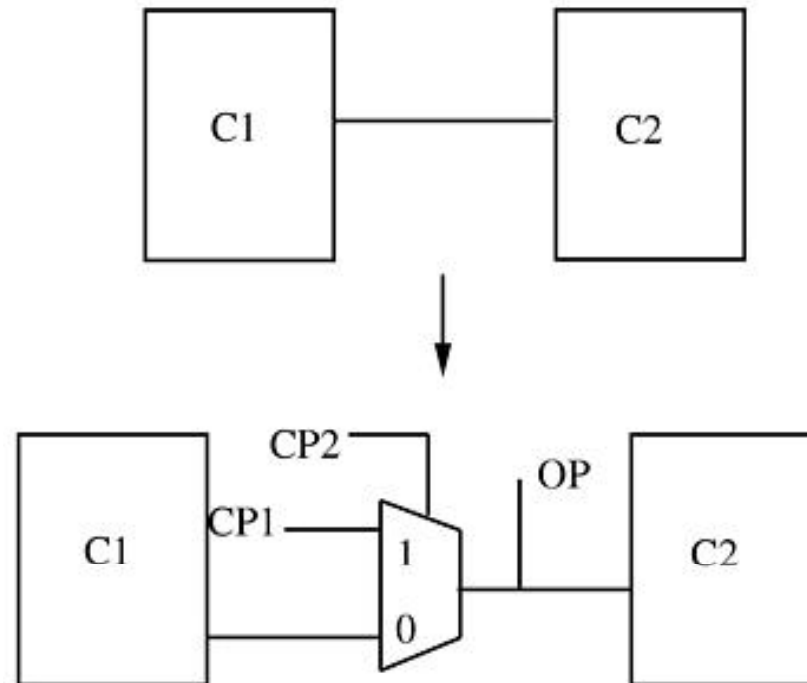
- ◆ **Disadvantages of ad-hoc DFT methods:**

- ✓ Experts and tools not always available.
- ✓ Test generation is often manual with no guarantee of high fault coverage.
- ✓ Design iterations may be necessary.



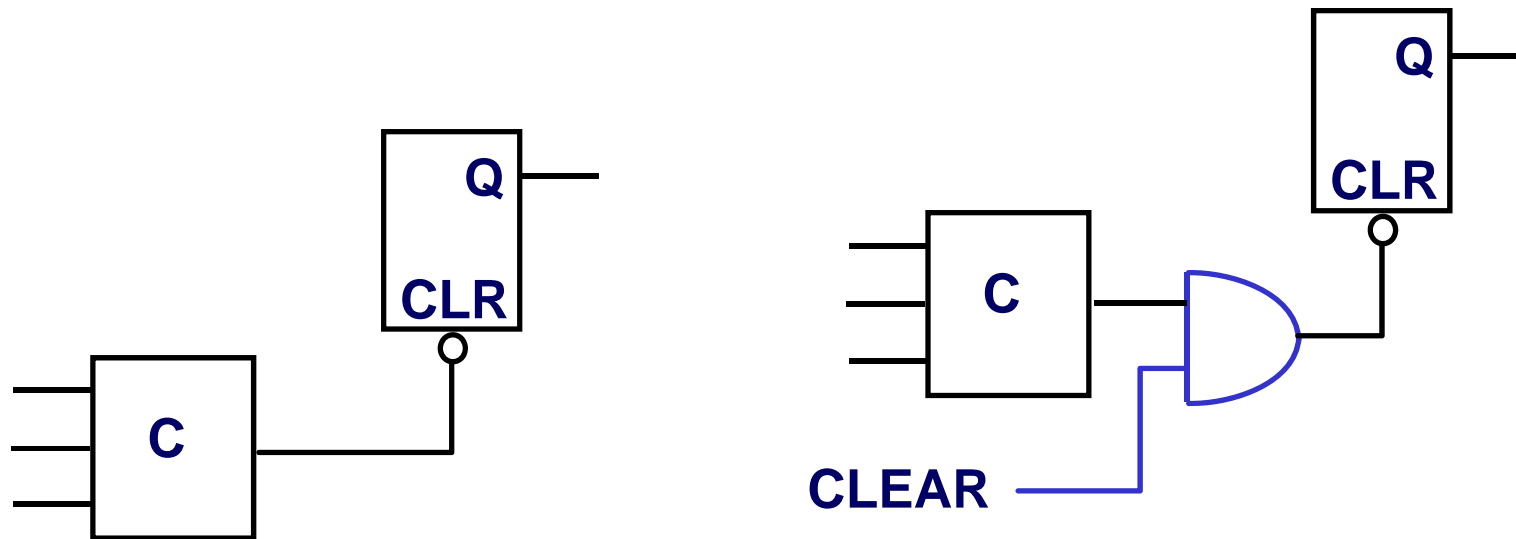
Test Points

- ◆ Employ test points to enhance controllability and observability
- ◆ Large demand on extra I/O pins
- ◆ Example



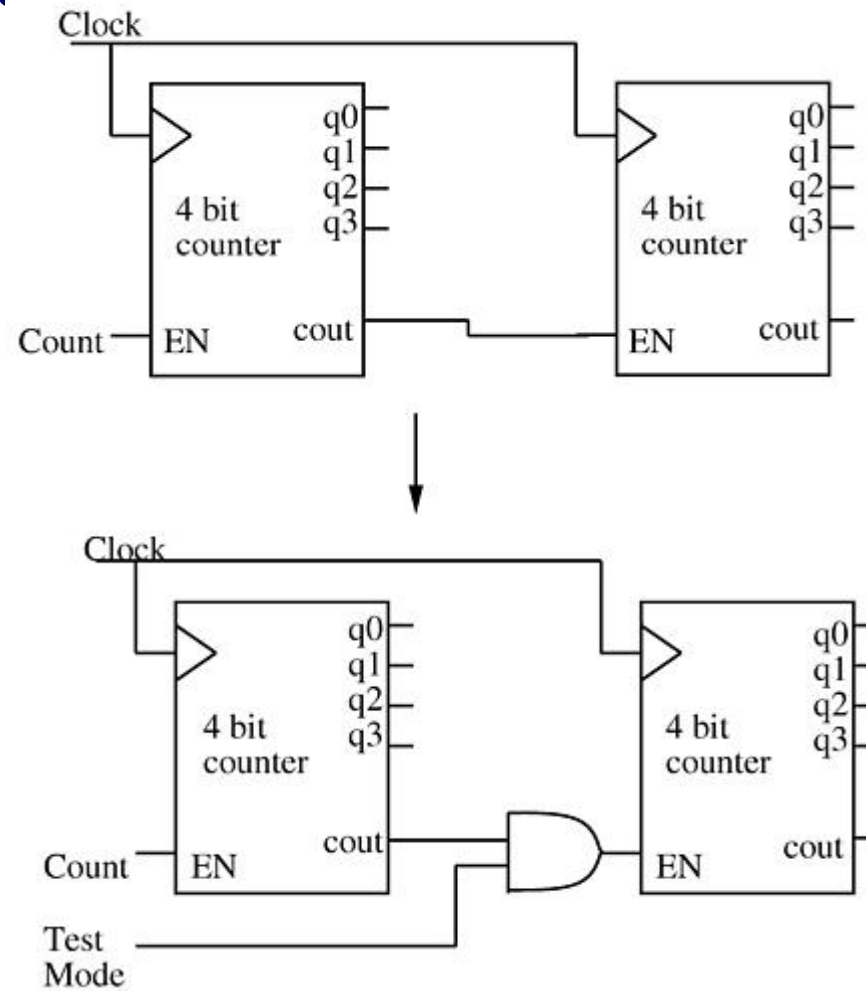
Initialization

- ◆ Flip-flop with explicit clear
 - Use explicit clear to all FFs



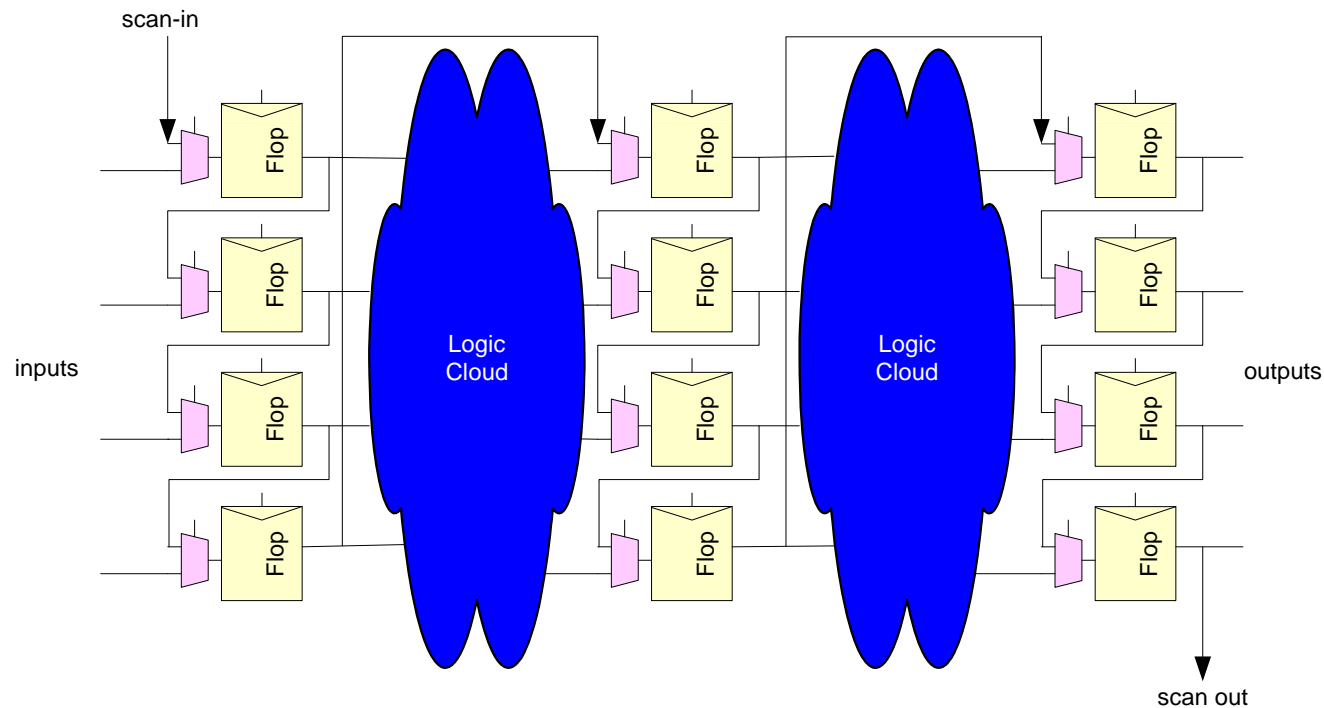
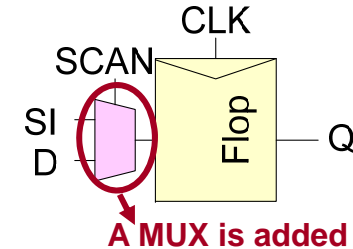
Partitioning

◆ Split large counters

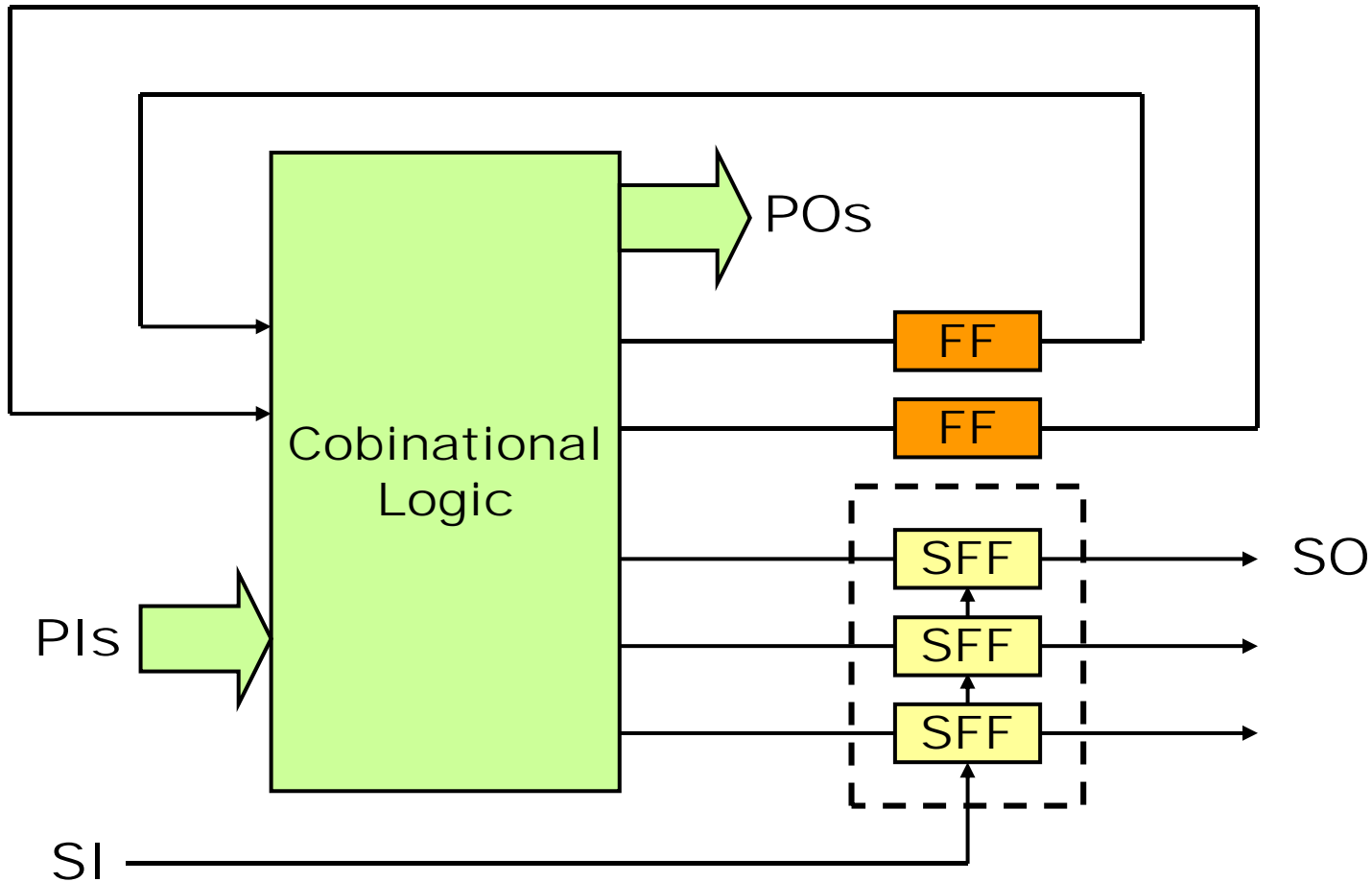


Scan Test

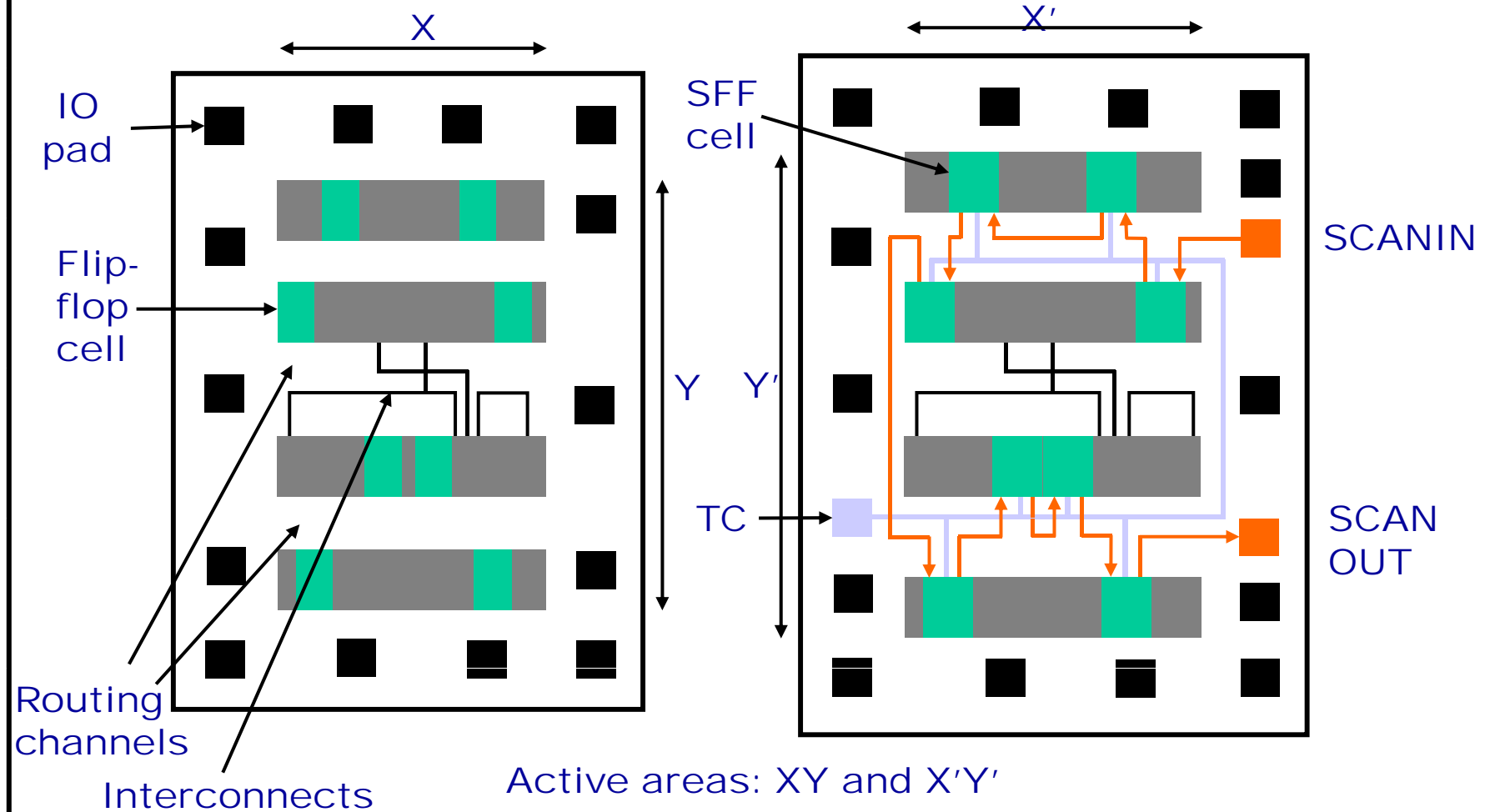
- ◆ **Convert each flip-flop to a scan register**
 - Only costs one extra multiplexer
 - Normal mode: flip-flops behave as usual
 - Scan mode: flip-flops behave as shift register
- ◆ **Contents of FFs can be scanned out and new values scanned in**



Partial Scan



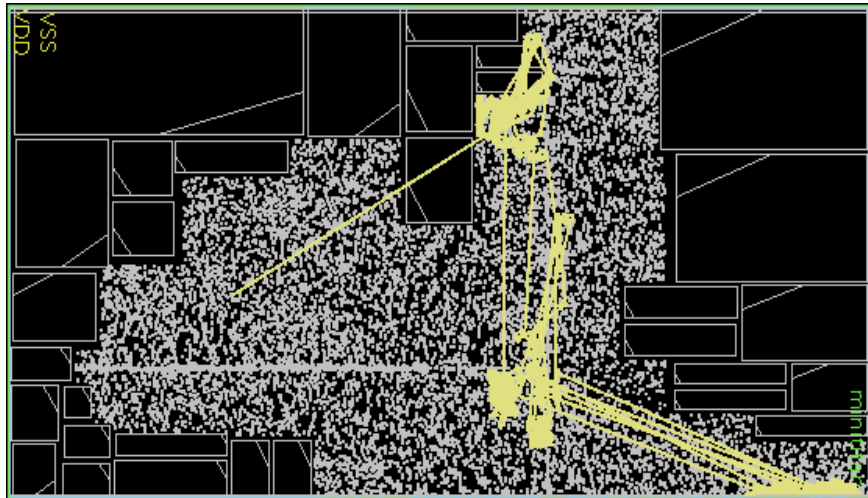
Optimum Scan Layout



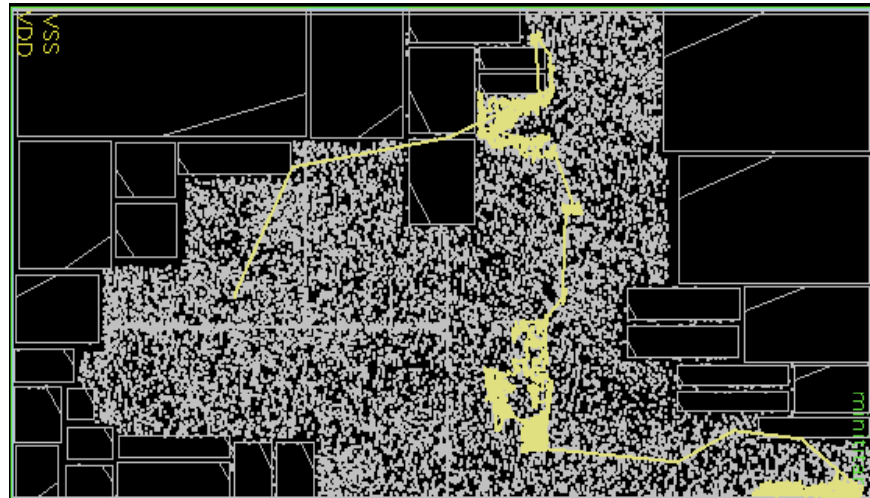
Scan Chain Reordering

- ◆ To reduce the routing congestions
- ◆ To reduce the hold-buffer insertion during placement
 - May need skew-based optimization

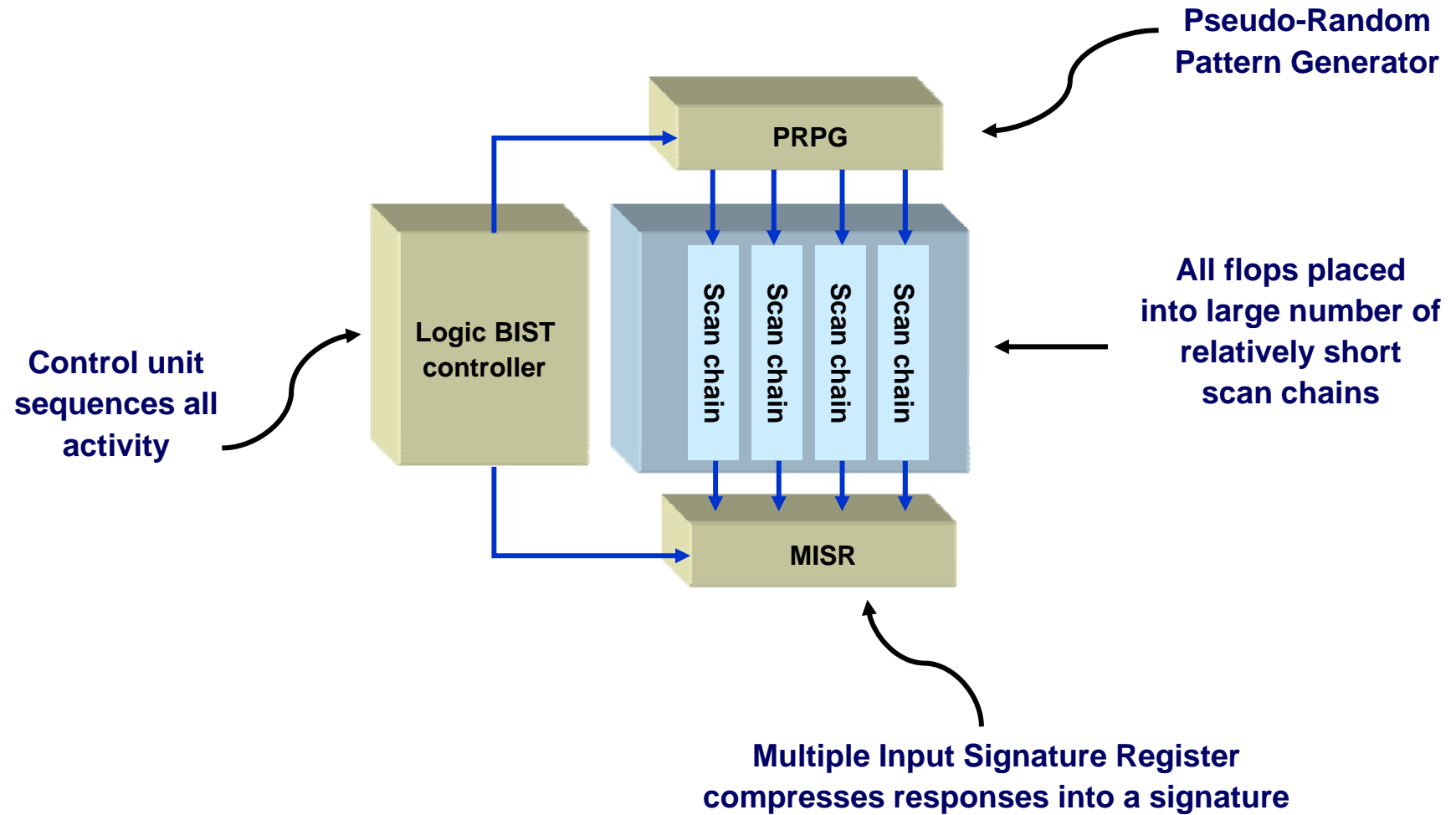
Before



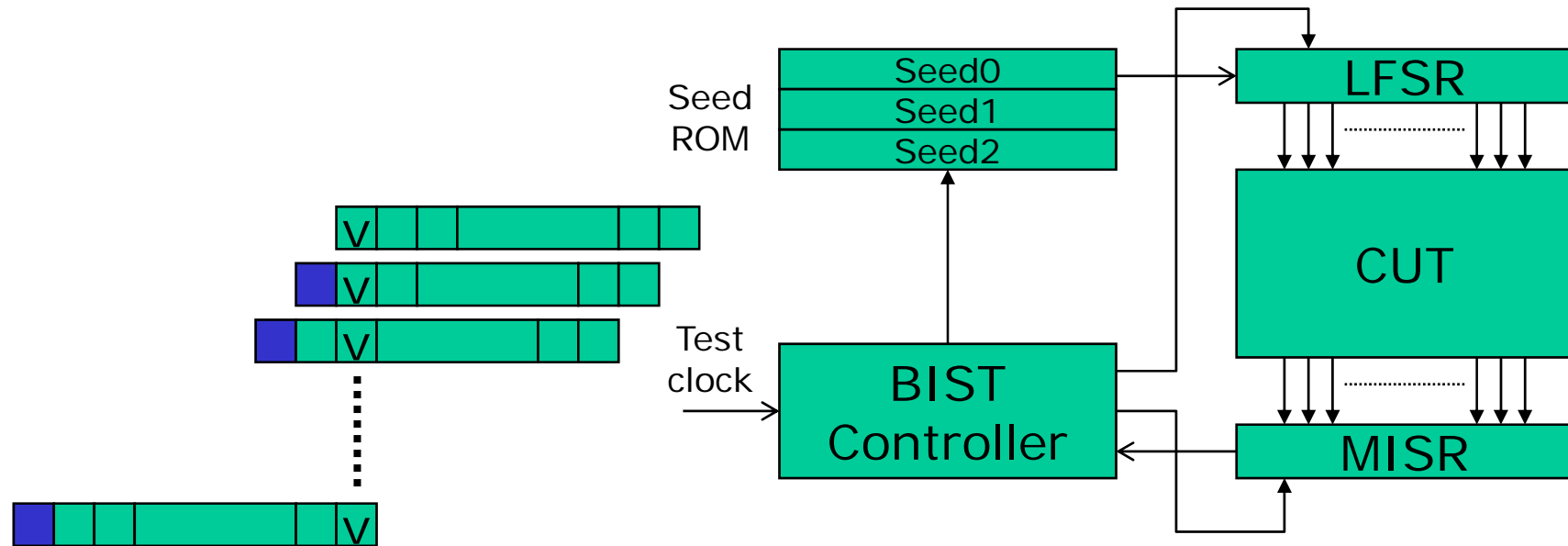
After



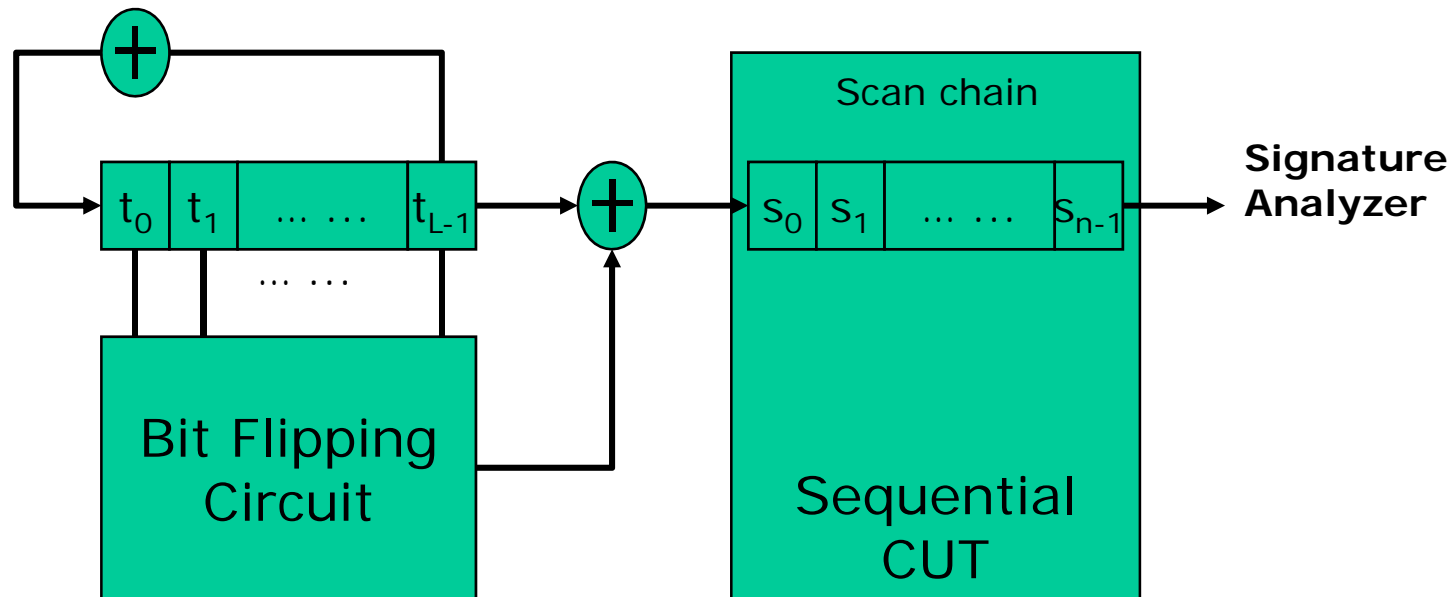
Logic BIST



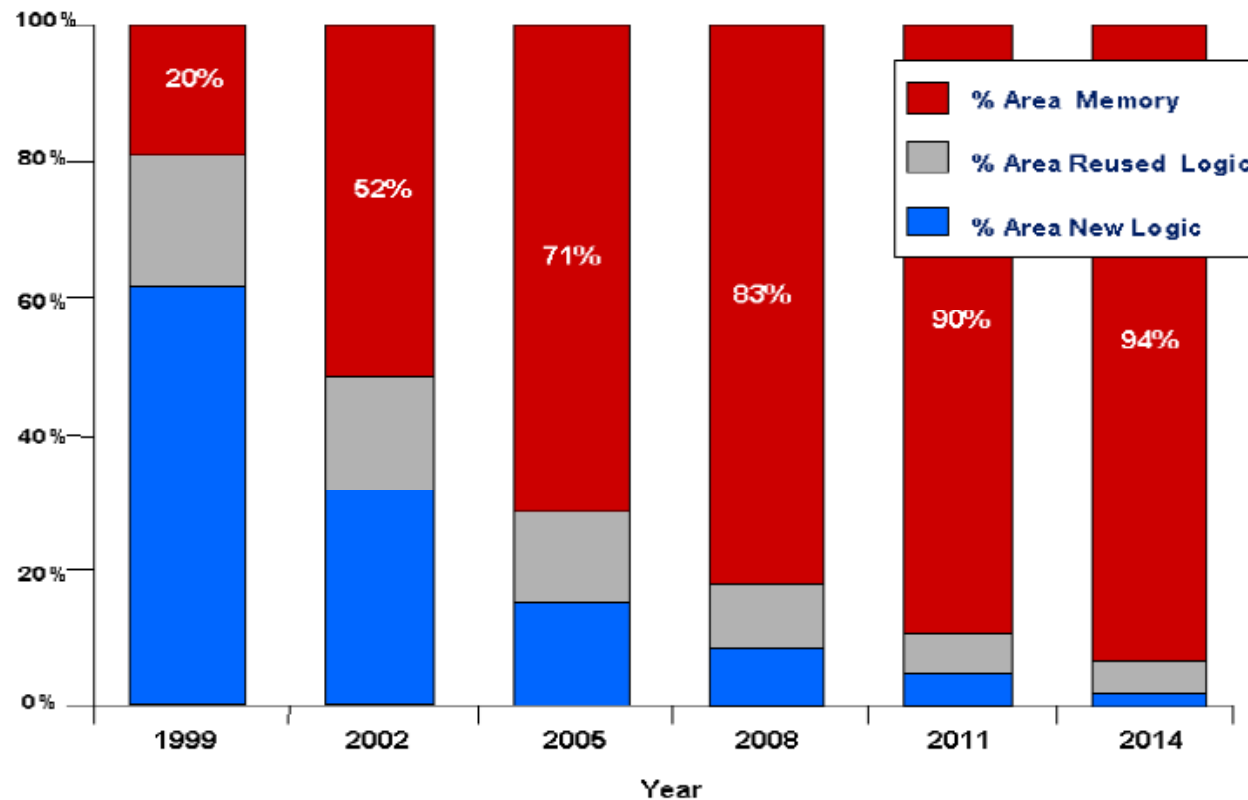
Multiple Seed / Reseeding



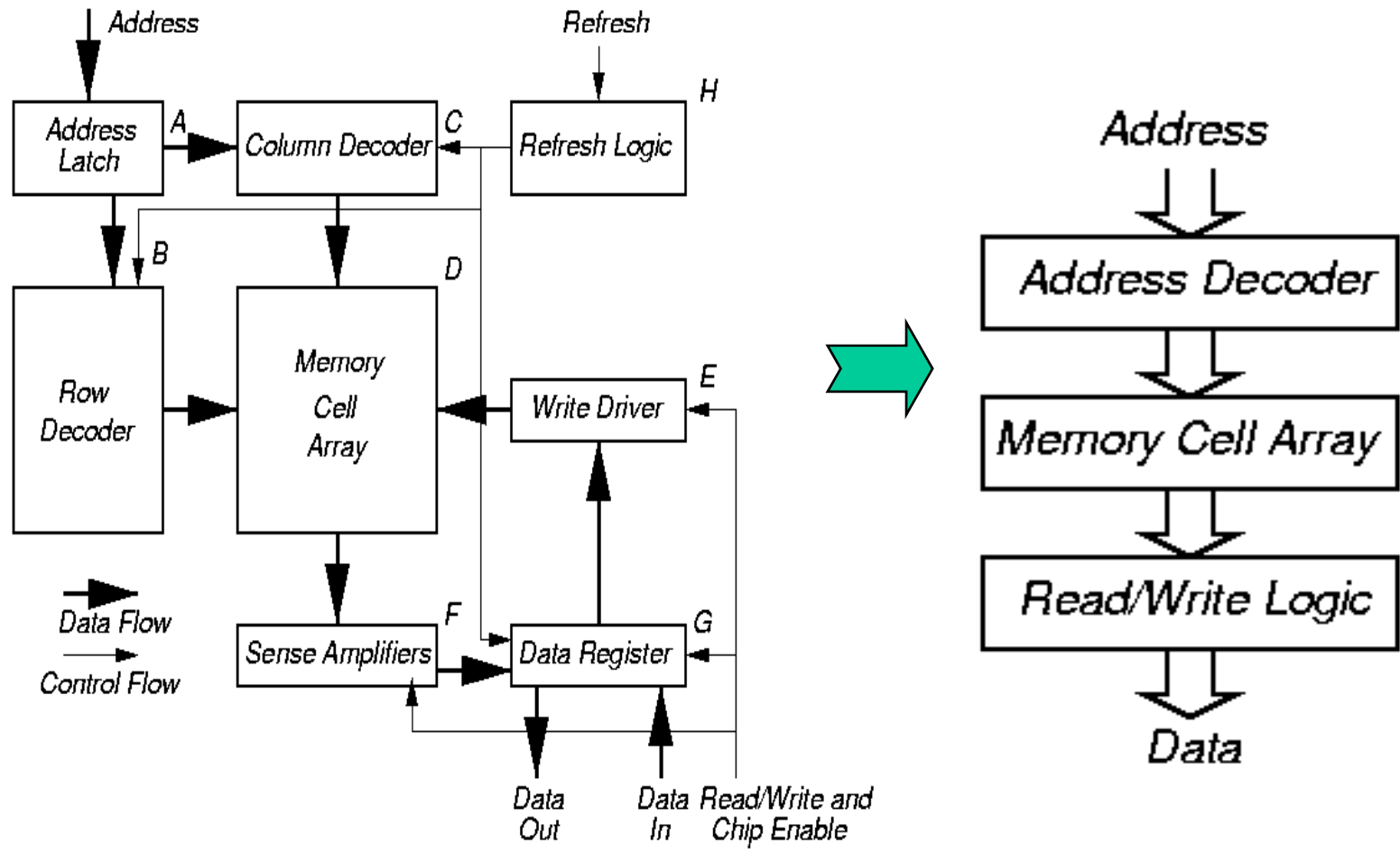
Bit Fixing/Bit Flipping Method



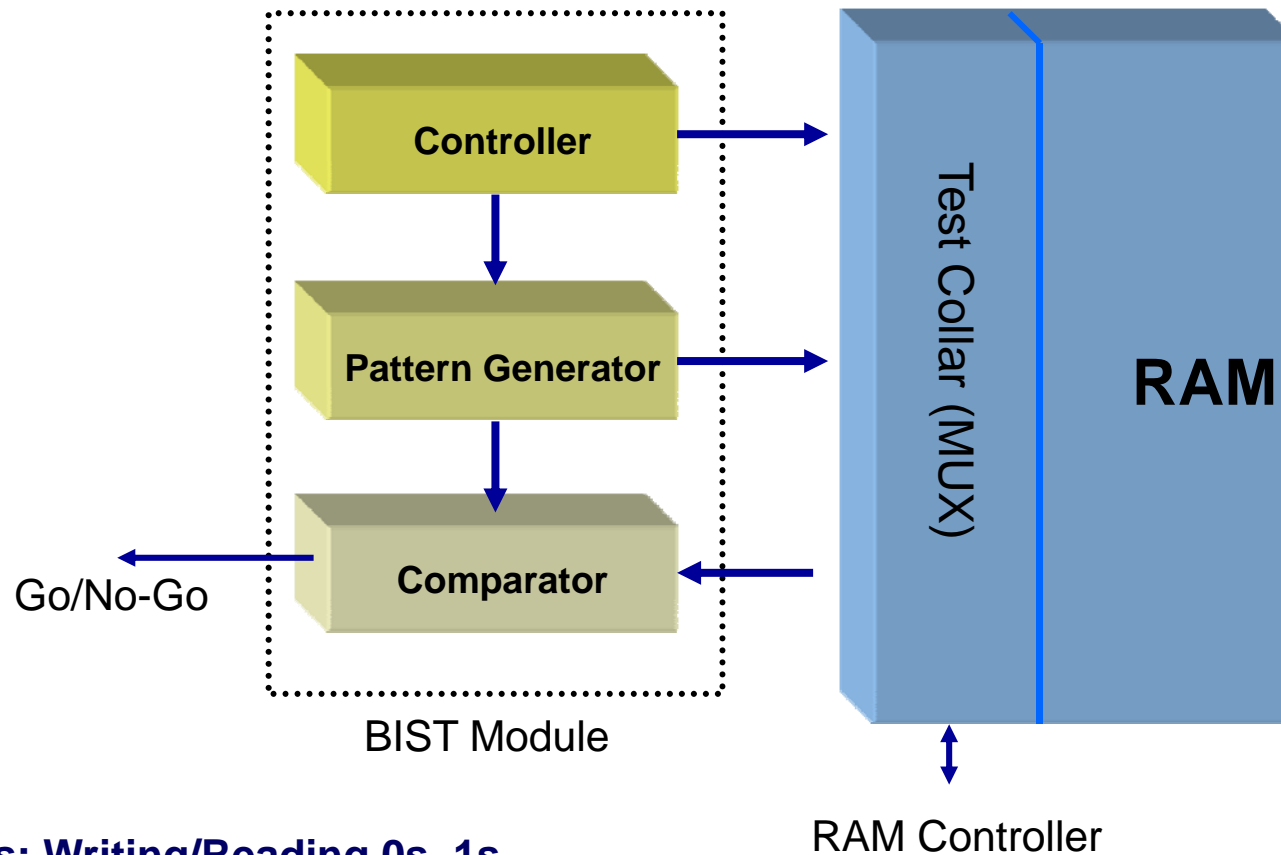
Embedded Memory in SOC



Memory Functional Model



Memory BIST Concept

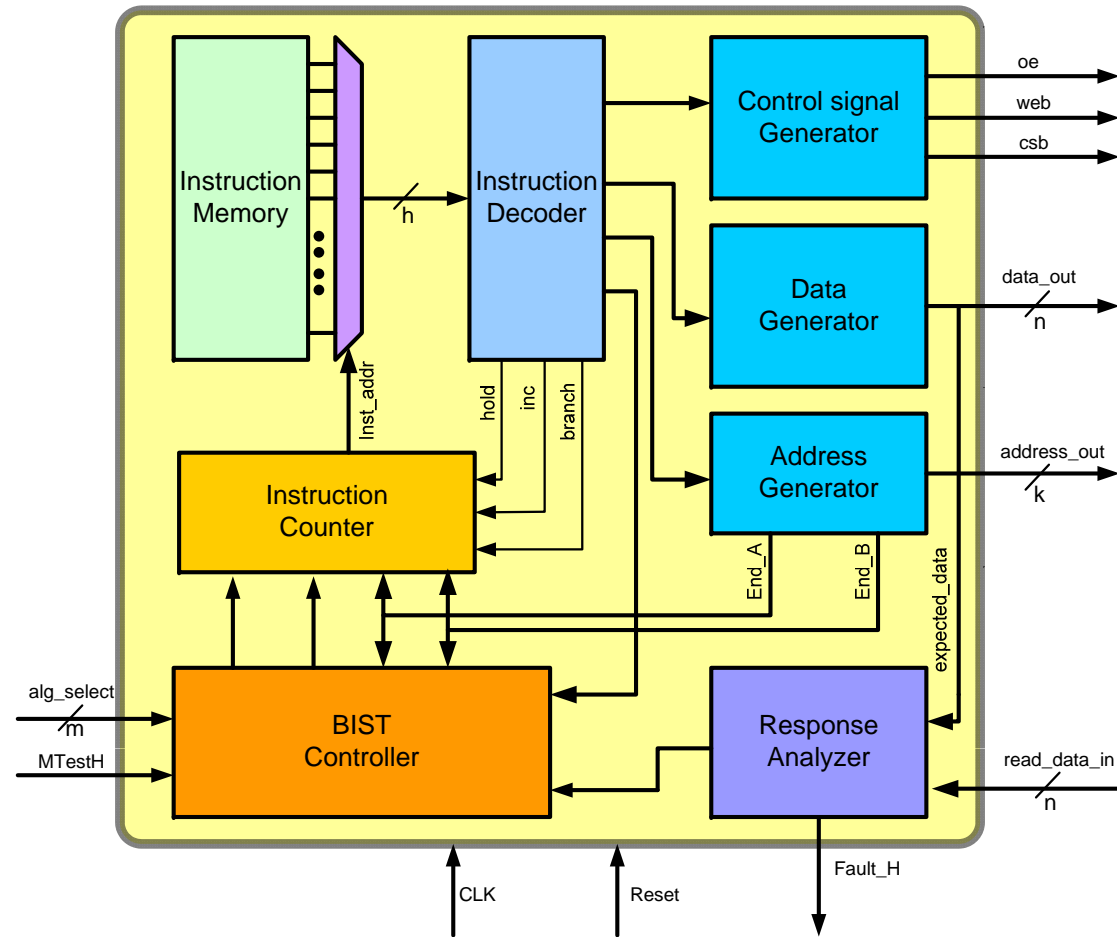


**Patterns: Writing/Reading 0s, 1s,
Walking 0s, 1s
Galloping 0s, 1s**



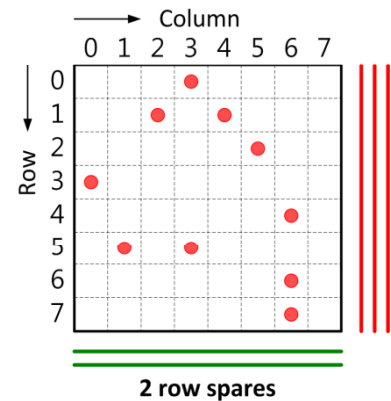
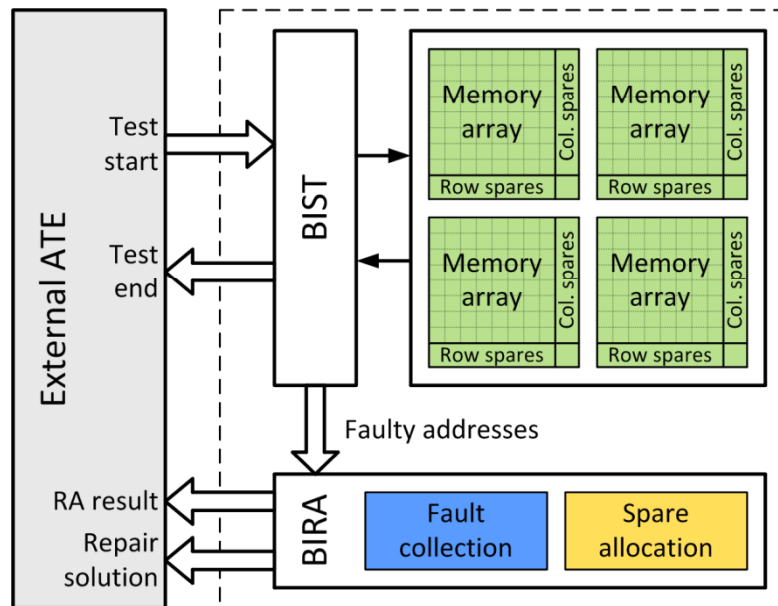
PMBIST

◆ Architecture

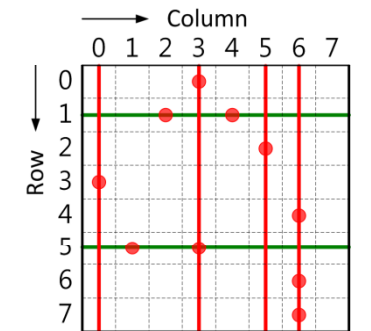


Built-In Redundancy Analysis (BIRA)

- ◆ 메모리 셀의 고장을 분석하고 여분의 셀을 이용해 고장을 수리하기 위한 효율적인 방법을 찾고자 함
- ◆ 수리 비용 및 시간의 단축을 위하여 **redundancy analysis** 방식을 **built-in**하여 메모리 셀을 수리 → **Hardware overhead** 및 **repair rate**의 고려가 필요
- ◆ 성능평가 기준: **repair rate, area overhead, rate of overused spares, analysis speed**



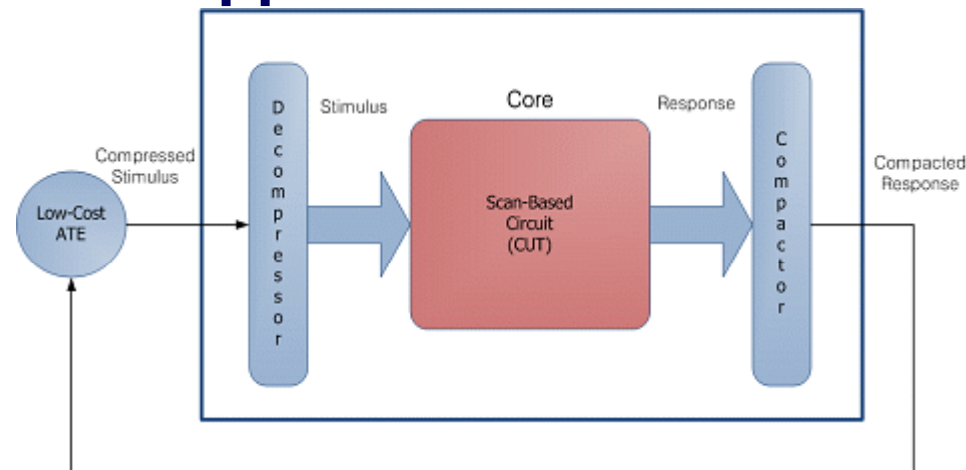
고장 수리 전 메모리



고장 수리 후 메모리

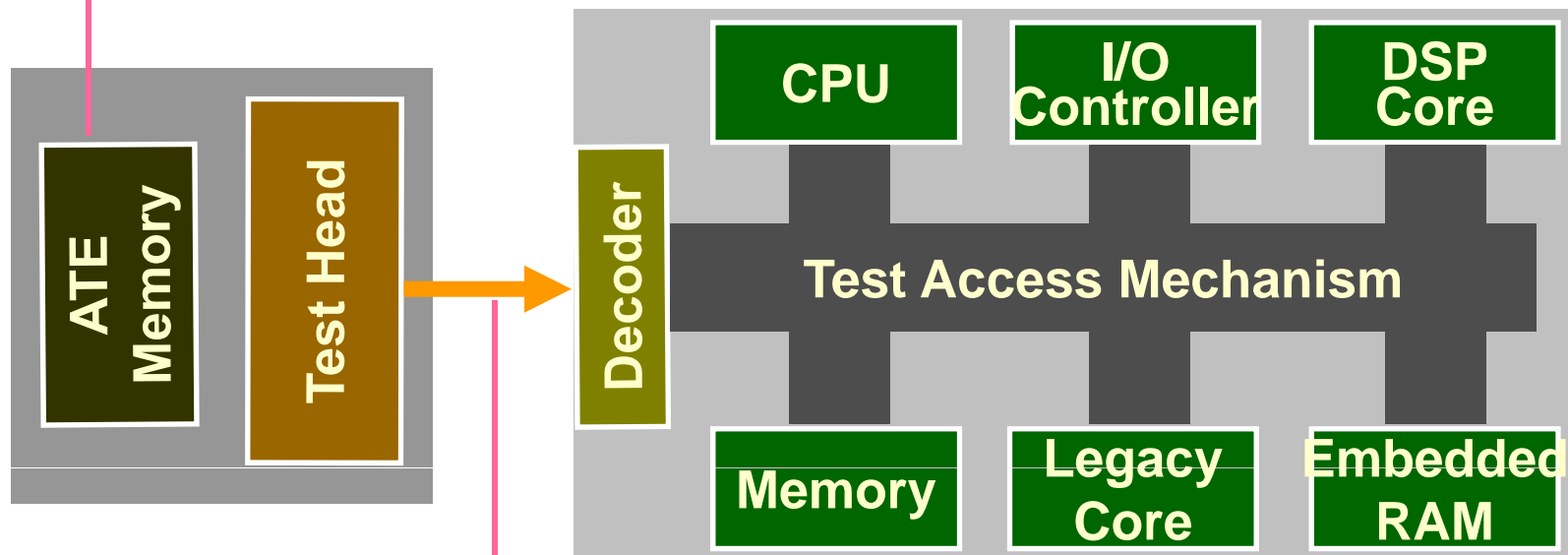
Test Compression

- ◆ **Compress the test input sequences**
- ◆ **Need a decompression units to make original test sequences**
- ◆ **Can be reduced for both limitations of ATE**
 - **The size of ATE memory**
 - **The width of ATE channel**
- ◆ **Can be reduced test application time**



Test Compression Concepts

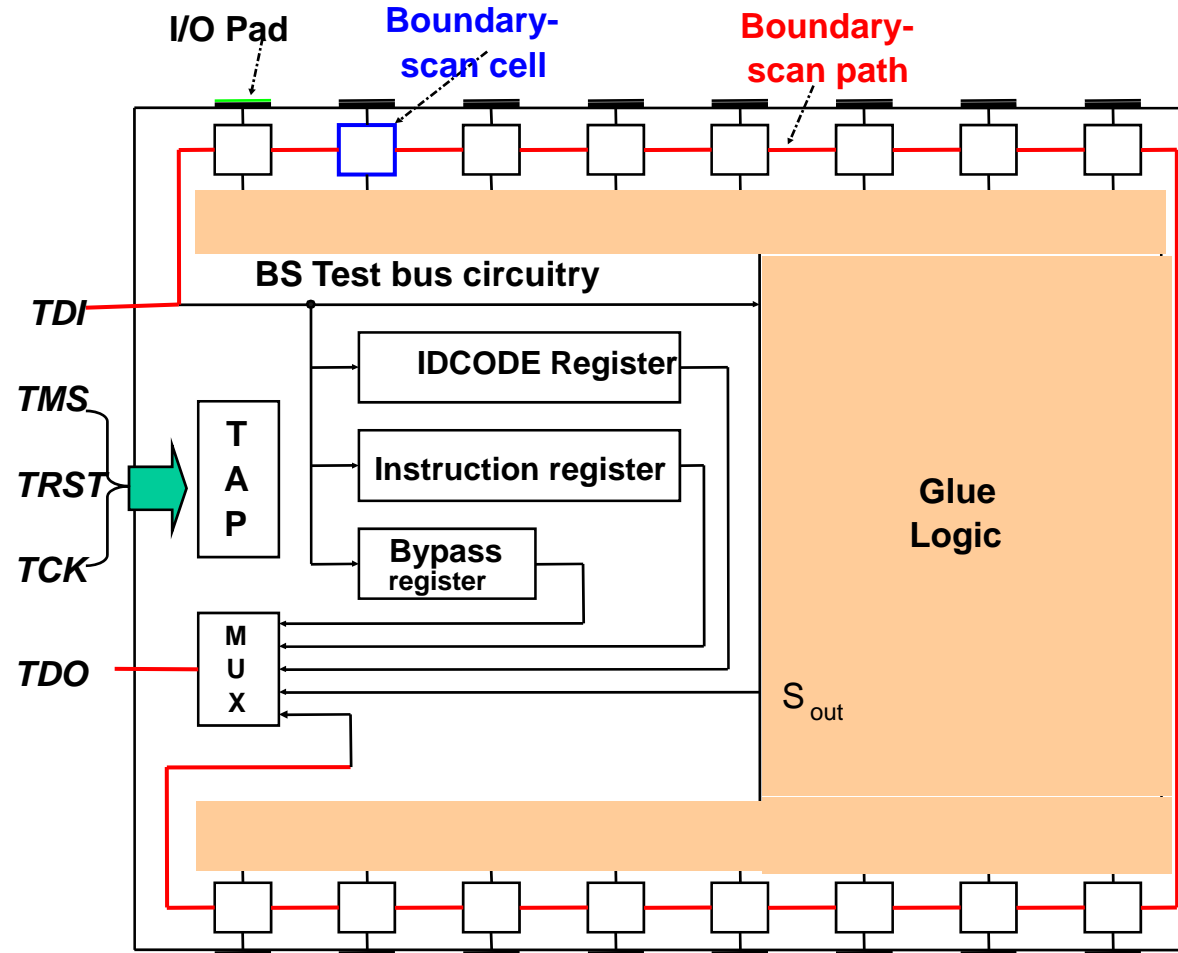
Smaller Memory (storing encoded test data)



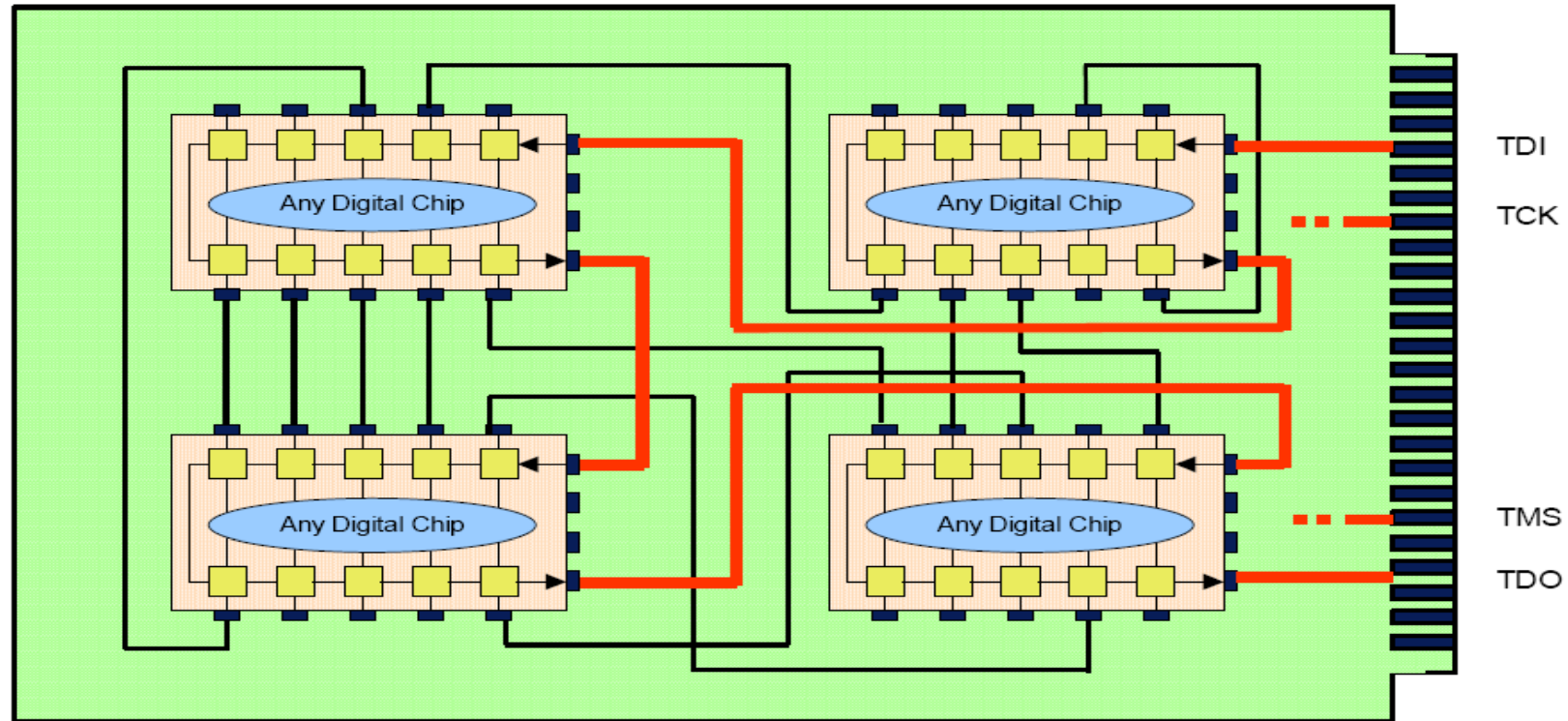
Lower bandwidth



IEEE 1149.1 Device Architecture

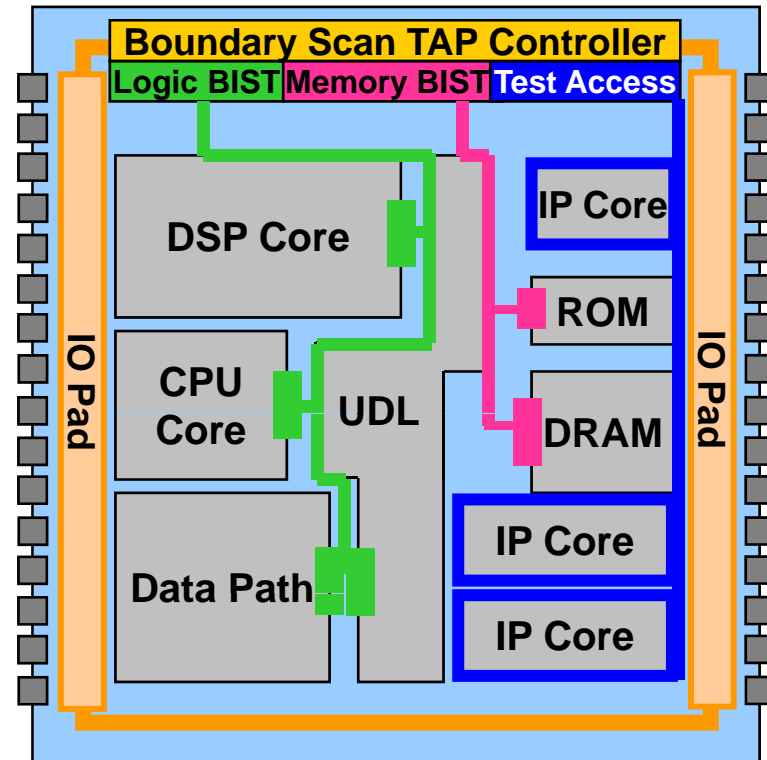


The Principle of BS Architecture



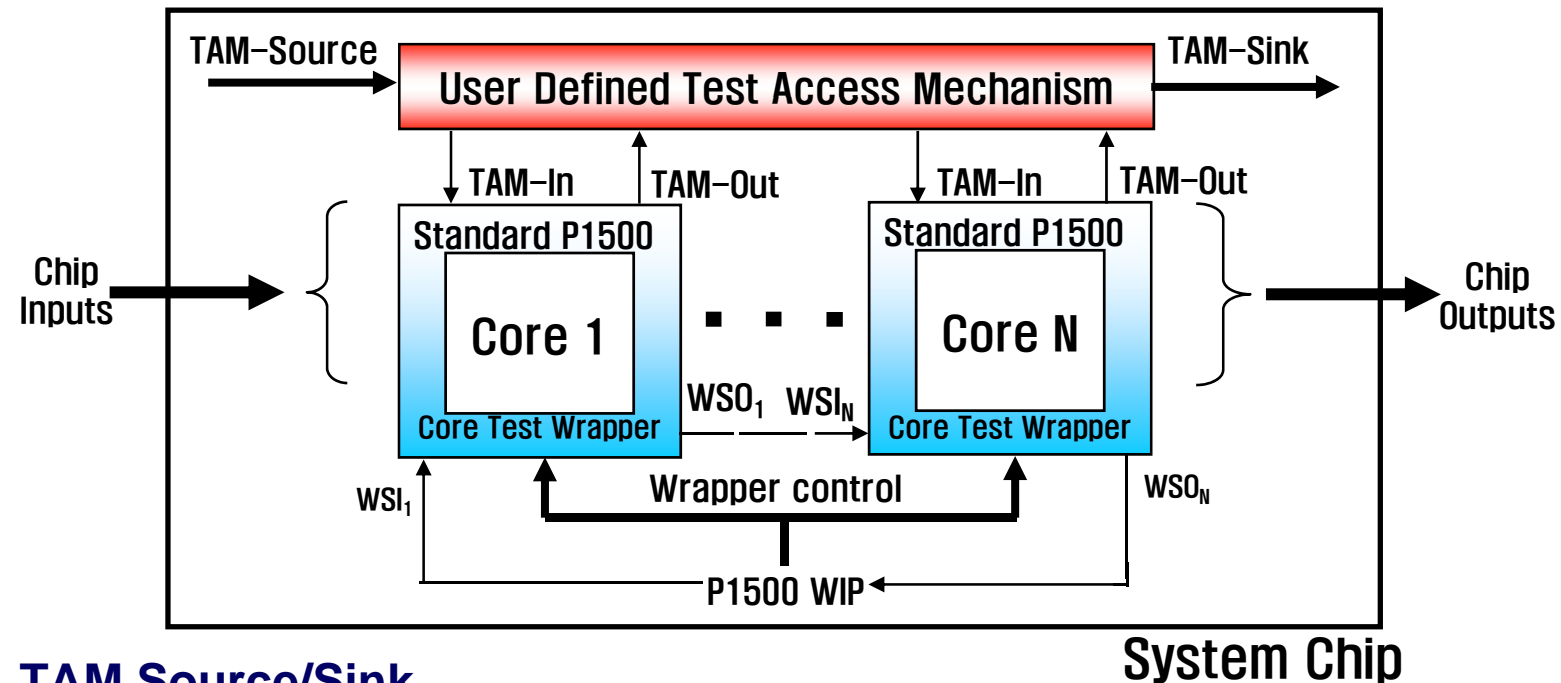
SOC Design Evolution

- ◆ Emergence of very large transistor counts on a single chip
- ◆ Mixed technologies on the same chip
- ◆ Creation of Intellectual Property (IP)
- ◆ Reusable IP-based design



SoC with P1500 Wrapped Cores

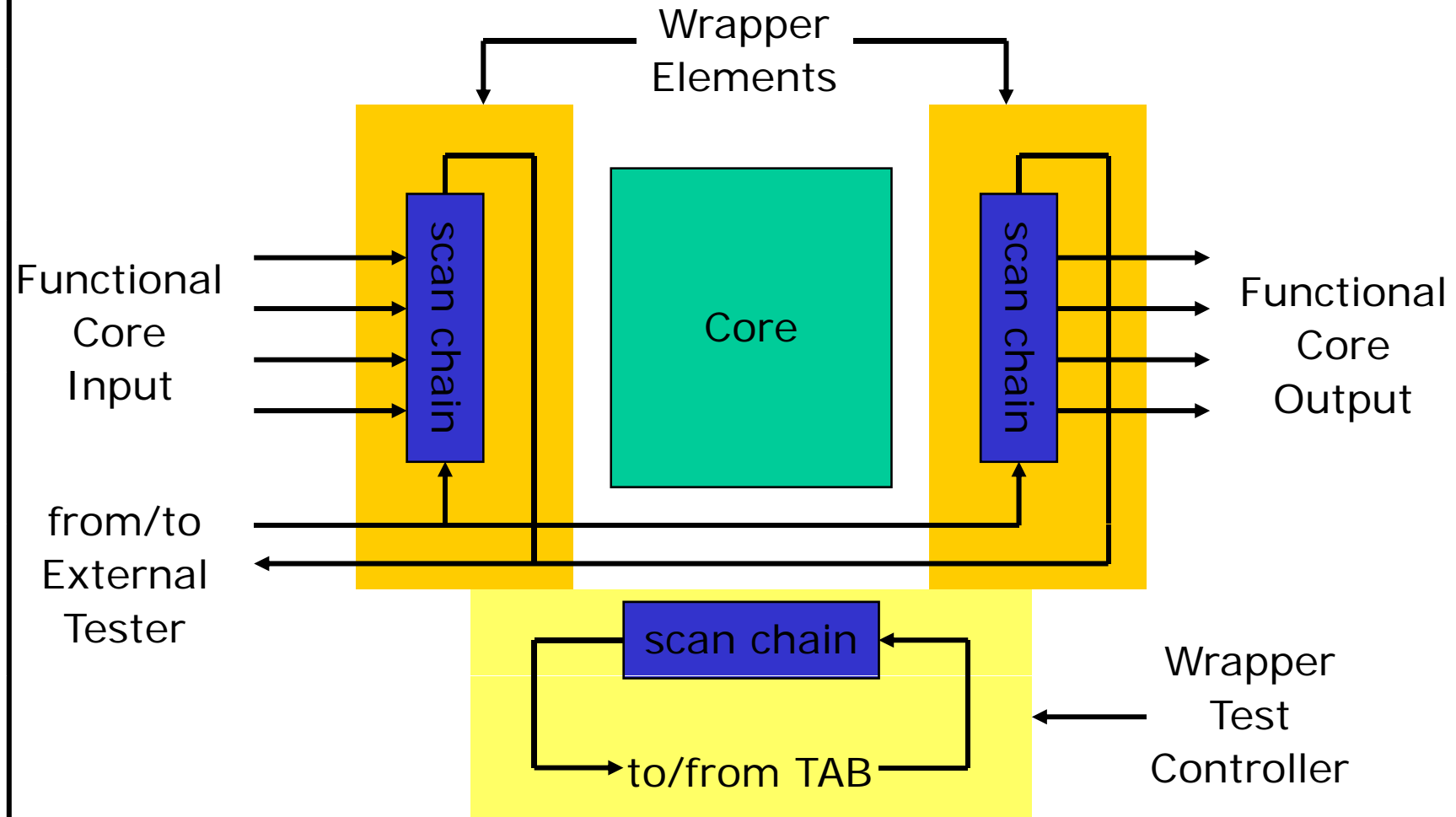
P1500



- ◆ **TAM Source/Sink**
 - From chip I/O, test bus/rail/port, BIST, etc..
- ◆ **TAM In/Out**
 - 0 to n lines for parallel and/or serial test data, or test control
- ◆ **P1500 Wrapper Interface Port (WIP)**
 - From chip-level TAP controller, chip I/O, ...

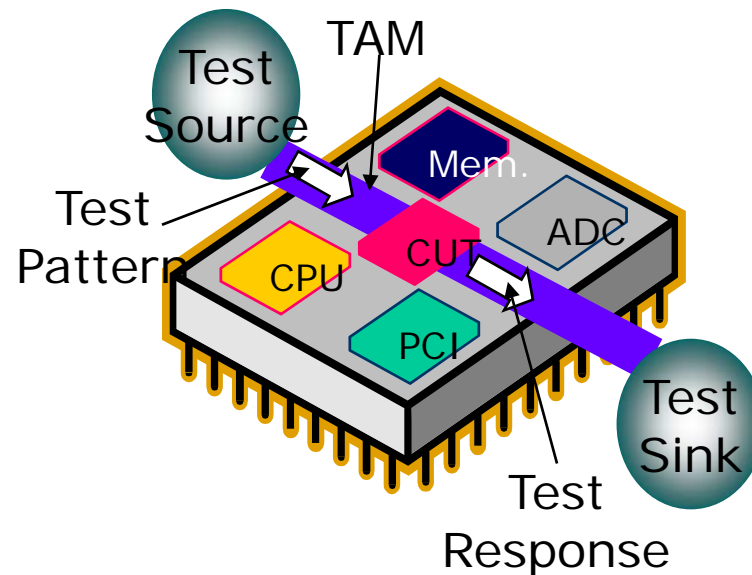


Test Wrapper



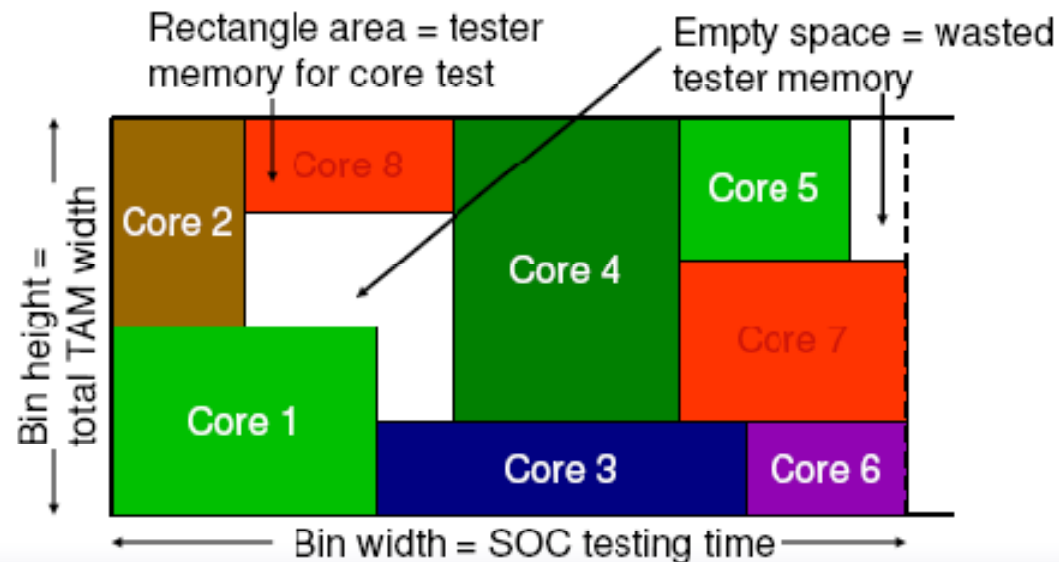
◆ Test access mechanism (TAM)

- Defined as user-defined test data communication structure
- Carries test signals from source to module, and module to sink
- Tests module interconnects via test-wrappers
- May contain bus, boundary-scan and analog test bus components.



- ◆ **Test scheduling problem**
 - Determine the minimal number of test sessions required to test all IPs
 - Determine the minimal colors that can be assigned to the nodes of a graph such that no edge connects two nodes of the same color
- ◆ **More complex when test time and power are considered**

Packed Bin = TAM Design + Test Schedule



Conclusion

